

## LED 导电胶 ZJ-L901C

### 主要用途 Applications

本品为用于发光二极管（LED）芯片贴装生产的导电胶产品，适用范围为手工点胶和自动点胶芯片贴装工艺。产品严格按照 ISO 质量管理体系要求生产。

*It is designed for LED die attaching process; particularly for plating transfer (pin transfer and back coating process) die attaching process. The stable manufacturing quality under ISO system ensures the good workability and application performance.*

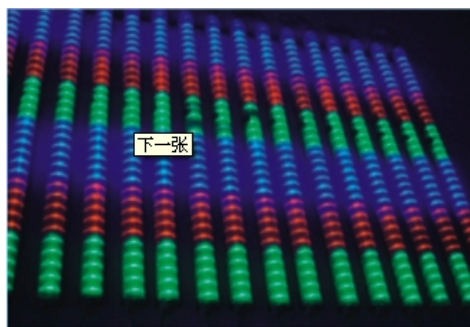


### 产品特点 Advantages

采用高端半导体芯片贴装胶粘剂技术，安全环保的无卤无重金属，工作性能好，导电性能优异，烘烤温度适中，粘结力强。



*Adopting advanced semiconductor packaging adhesive technology, which is halogen-free and non-heavy metal formula with features of good workability, good conductivity, moderate baking temperature, strong adhesion.*



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## 产品测试参数 Test Data

项目 Items	测试条件 Test Conditions	数值 Value	单位 Unit
含银量 Silver Content	TGA	75 +/- 2	wt%
比重 Density		3.5	g/ml
最大粒径	刮板法	8	μm
运动粘度 Viscosity	Brookfield, 25℃, 5 rpm	17,000+/- 2,000	厘泊
动态触变指数	25℃, Vis.0.5rpm/Vis.5rpm		-
离子含量, ) Cation Content Na <sup>+</sup> K <sup>+</sup> NH <sub>4</sub> <sup>+</sup> Cl <sup>-</sup>	水萃取法 Water extraction	<4 <1 <3 <1	ppm
推荐固化温度/推荐固化时间 Curing Temperature/Curing Time	-	150/2	℃/hour 摄氏度/小时
体积电阻率 Volume Resistivity	四点法/four point	0.0002~0.0008	欧姆•厘米 Ω•cm
推荐存储条件 Storage Condition	-	-40±1	℃
存储寿命 Shelf Life	-	12	月 months
工作寿命 Work Life	室温/RT	>72	小时 hour
芯片切向粘结力	室温 150℃	TBD	
固化失重 Weight loss during cure	空气气氛加热到 800 摄氏度	20.17	%
玻璃化转变温度 Tg Glass transition temperature	零下 50 摄氏度加热到 300 摄氏度	255	摄氏度 ℃
模量 modulus		TBD	



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## 应用说明

## APPLICATION GUIDELINES

### 包装 PACKING

本产品的包装形式为塑料针管包装和罐装，以及客户所特别要求的形式。容量规格分别为 10ml（针筒，30 克），30ml（针筒，90 克），300 ml（罐，1 磅）等。

*Product is packed into plastic syringes or jars, and the one customer require. The quantity are 10ml (syringe, 30g), 30ml (syringe, 90g), 300ml (jar, 1pound).*

### 运输 SHIPMENT

本产品的运输前需把产品包装后放入适量干冰中，运输过程必须采用干冰保护，其温度处于零下 80 摄氏度。如果干冰在运输过程中完全挥发，则产品品质有可能发生改变甚至完全失效。运输结束后，丢弃干冰包装并置于零下  $40 \pm 1$  摄氏度的低温冰柜储存。

*This product is packed and shipped in proper amount dry ice at  $-80^{\circ}\text{C}$ . If the dry ice has disappeared during the shipment, the product quality maybe changes. If so, please contact Nonfemet for advice. After shipment, please place the product in freezer at  $-40 \pm 1^{\circ}\text{C}$ .*

### 存储 STORAGE

产品必须存储于零下  $40 \pm 1$  摄氏度以保证存储期和产品质量。不正确的存储会造成使用性能和固化性能的下降。产品在存储过程中应采用正常位置，不可倒置和侧倒。

*This product must be stored at  $-40 \pm 1^{\circ}\text{C}$  for good shelf life and quality. Incorrect storage conditions will degrade the performance of the material in both handling and final cured properties. The container has to be placed in the right way.*

### 解冻 THAWING

产品在使用前需达到室温。根据包装规格不同，10ml，30ml，300ml 装推荐分别至少解冻 30 分钟，1 小时和 2 小时。在达到室温以前不要打开盖子。打开盖子以前需要清除掉容器外所有水珠。不要重复解冻，解冻以后的胶不可以再次冷冻。

*Allow the container to reach room temperature before using. 10CC package needs 30 minutes to be thawed, 30CC needs 1 hour, and 300ml needs 2 hours. Do NOT open the container before contents reach ambient temperature. Any moisture that collects on the*



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*thawed container should be removed prior to opening the container. Do NOT re-freeze. Once thawed to room temperature, the adhesive should not be re-frozen.*

## **产品使用 ADHESIVE APPLICATION**

解冻后的胶必须立即使用于点胶。如果胶盘中有以前的胶，应清除以减少混合。导电胶应在使用有效期内用完。为达到合适的胶层厚度和 25% - 50%包边高度，应调节合适胶量。

*Thawed adhesive should be immediately placed on dispense equipment for use. If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive. Adhesive must be completely used within the product's recommended work life. Apply enough adhesive to achieve a proper wet bond line thickness, dispensed with approximately 25% - 50% filleting on all sides of the die.*